

Electronic Device Cooling Fan with Heatsink

This cooling fan and heatsink provides efficient heat dissipation in electronic devices. It features a multi-layered heatsink structure with an integrated fan for enhanced airflow.



Overview

High-Performance Thermal Management

This cooling solution is engineered for efficient heat dissipation in sensitive electronic devices. Featuring a multi-layered heatsink structure combined with an integrated fan, it ensures optimal airflow and heat transfer. It is designed to maintain stable operation and extend the lifespan of critical components like computer processors and power amplifiers.

Technical Specifications

Cooling Method	Active cooling with integrated fan and heatsink
Construction Material	High thermal conductivity

Applications

Compatible Applications

- Computer processors
- Power amplifiers
- Heat-sensitive electronic components

Key Features

Performance Highlights

1 High Efficiency

Heat Dissipation

1 Integrated

Airflow Design